

NOTE5. PRODUCTION LOT No. & MODIFY CODE AS INDICATED.
(Ex. LOT NO.) I 5 Y B

LOT NUMBER OF CURRENT DAY (SEE TABLE 4)
MONTH (1 TO 9 FOR JAN. TO SEPT, RESPECTIVELY, OCT.:0, NOV.:X, DEC.:Y)
YEAR (LAST DIGIT ONLY)
MANUFACTURE CODE

(DESIGNATION) S M 3 A

KEY POSITION TYPE: A, B, E, M

SERIES PREFIX

DESIGNATION

SM3ZS067U410**

SERIES シリーズ
Z: LIF TYPE
Z: 低挿入タイプ
S: STANDARD
NO. OF CONTACTS 芯数
MOUNTING TYPE 実装タイプ
U: ON BOARD TYPE

KEY POSITION TYPE: A, B, E, M

CONTACT FINISH 接点仕上げ
A: Au (0.13 μm MIN)
B: Au (0.25 μm MIN)

PRODUCT HEIGHT 製品高さ
215: 2.15mm
310: 3.10mm
410: 4.10mm

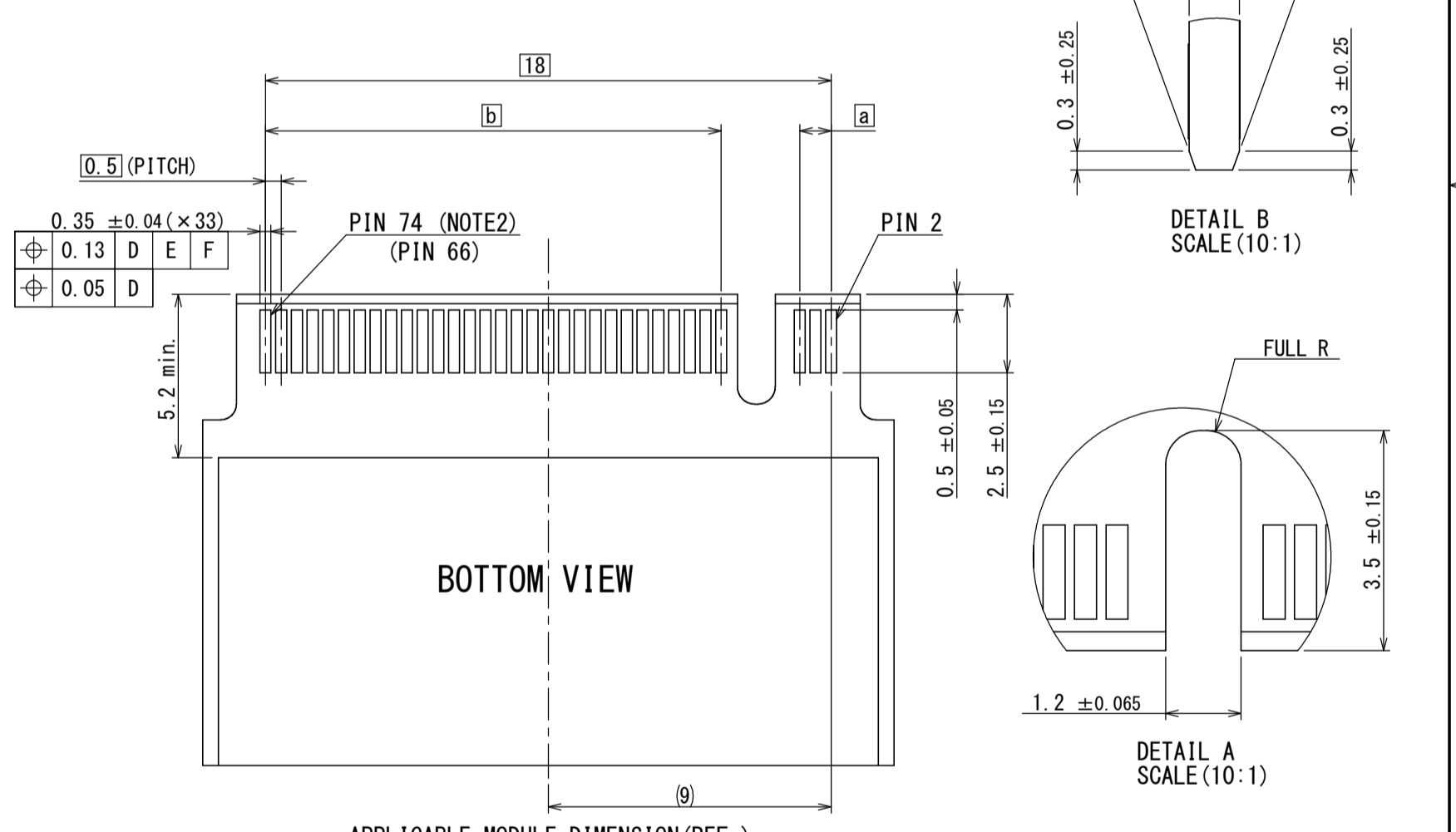
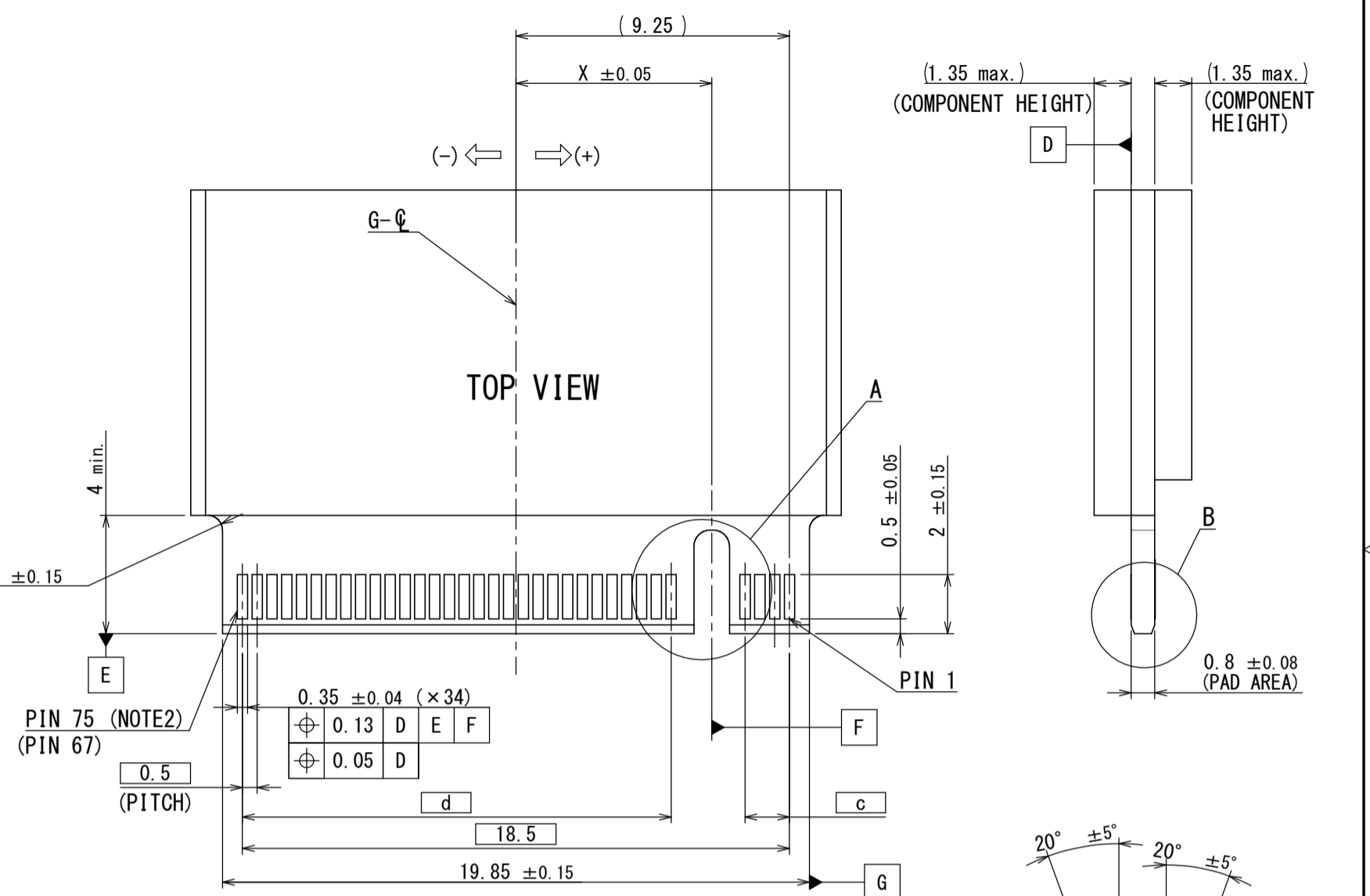
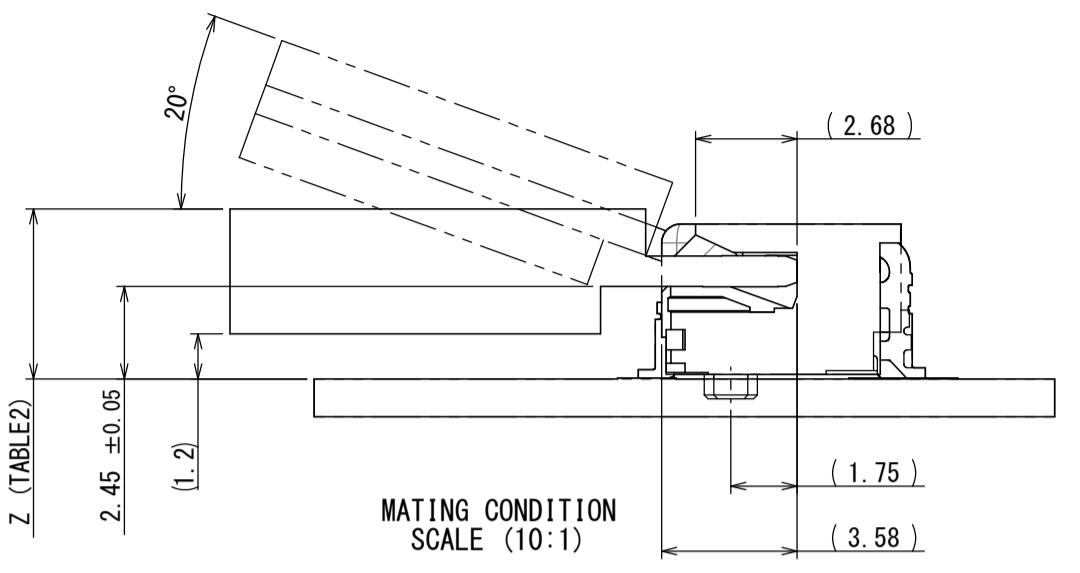
TABLE 1

KEY#	X	a	b	c	d
A	+6.625	1	14.5	1.5	14.5
B	+5.625	2	13.5	2.5	13.5
E	+2.625	5	10.5	5.5	10.5
M	-6.125	14	1.5	14	2

TABLE 2

COMPONENT HEIGHTS FOR MODULES	Z
1.2 MAX	4.55 MAX RSS
1.35 MAX	4.70 MAX RSS
1.5 MAX	4.85 MAX RSS

NOTE1. THE COPLANARITY OF CONTACT AND HOLD DOWN SHALL BE 0.1 MAXIMUM ON THE SURFACE TABLE.
NOTE2. THIS NUMBER IS PIN-OUT NUMBER DEFINED BY NGFF SPECIFICATION.
NOTE3. THIS CONNECTOR IS HALOGEN FREE CORRESPONDENCE PRODUCT.
NOTE4. THIS AREA SHALL NOT SHOW ANY BURRS AND UNEVEN SURFACE BY EJECTOR PIN MARK, TOOL PARTING LINE, AND ANY OTHER FACTORS.



APPLICABLE MODULE DIMENSION (REF.)
SCALE (5:1)

NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	HOLD DOWN	2	COPPER ALLOY	TIN PLATING OVER Ni	
3	TOP SIDE CONTACT	34	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
2	BOTTOM SIDE CONTACT	33	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
1	INSULATOR	1	THERMO PLASTIC		

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE) 08/JAN/2013	尺度 (SCALE) 5:1	シリーズ (SERIES) SM3	日本航空電子工業株式会社
一般公差 (GENERAL TOLERANCE)	製図 DR.	名称 (TITLE) SM3ZS067U410** (NGFF Double-Sided modules)		JAE JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
寸法 (DIMENSION): ±0.8 × ±0.4 ×× ±0.1 ××× ±	担当 CHK. S. YAMAGUCHI	質量 (MASS)		
角度 (ANGLES): ×° ± ××' ±	査閲 APPD. R. KATOU	承認 APPD. T. SHINDOU		図面番号 (DRAWING NO.) SJ113503
単位 (UNIT): mm				版数 (VER.) 1